5V TTL to Differential PECL Translator

Description

The MC10ELT/100ELT20 is a TTL to differential PECL translator. Because PECL (Positive ECL) levels are used, only +5 V and ground are required. The small outline 8-lead package and the single gate of the ELT20 makes it ideal for those applications where space, performance, and low power are at a premium.

The 100 Series contains temperature compensation.

Features

- 1.2 ns Typical Propagation Delay
- PNP TTL Inputs for Minimal Loading
- Flow Through Pinouts
- Operating Range: $V_{CC} = 4.75 \text{ V}$ to 5.25 V with GND = 0 V
- Pb-Free Packages are Available



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MARKING DIAGRAMS*



SO-8 D SUFFIX CASE 751







TSSOP-8 DT SUFFIX CASE 948R







DFN8 MN SUFFIX CASE 506AA

H = MC10 K = MC100

5B = MC10 2P = MC100

1

A = Assembly LocationL = Wafer LotY = Year

W = Work Week

M = Date Code= Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

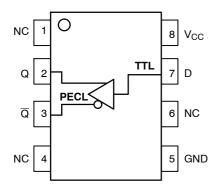


Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

Table 1. PIN DESCRIPTION

Pin	Function
Q, \overline{Q}	PECL Differential Outputs*
D	TTL Input
V _{CC}	Positive Supply
GND	Ground
NC	No Connect
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

^{*}Output state undetermined when inputs are open.

Table 2. ATTRIBUTES

Characterist	Va	lue				
Internal Input Pulldown Resistor	N/A					
Internal Input Pullup Resistor		N	/A			
ESD Protection		kV 00 V				
Moisture Sensitivity, Indefinite Time	Out of Drypack (Note 1)	Pb Pkg	Pb-Free Pkg			
	SO-8 TSSOP-8 DFN8	Level 1 Level 1 Level 1	Level 1 Level 3 Level 1			
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0	@ 0.125 in			
Transistor Count	51 De	evices				
Meets or exceeds JEDEC Spec EIA	Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test					

^{1.} For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Power Supply	GND = 0 V		7	V
V _{IN}	Input Voltage	GND = 0 V	$V_{I} \leq V_{CC}$	7	V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SO-8 SO-8	190 130	°C/W °C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	SO-8	41 to 44	°C/W
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44	°C/W
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T _{sol}	Wave Solder Pb Pb-Free	< 3 s @ 248°C < 3 s @ 260°C		265 265	°C
θЈС	Thermal Resistance (Junction-to-Case)	(Note 2)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

^{2.} JEDEC standard multilayer board – 2S2P (2 signal, 2 power)

Table 4. 10ELT SERIES PECL DC CHARACTERISTICS $V_{CC} = 5.0 \text{ V}$; GND = 0.0 V (Note 3)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Icc	Power Supply Current			16			16			16	mA
V _{OH}	Output HIGH Voltage (Note 4)	3920	4010	4110	4020	4105	4190	4090	4185	4280	mV
V _{OL}	Output LOW Voltage (Note 4)	3050	3200	3350	3050	3210	3370	3050	3227	3405	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 3. Output parameters vary 1:1 with $V_{CC}.\ V_{CC}$ can vary $\pm 0.25\ V.$
- 4. Outputs are terminated through a 50 Ω resistor to V_{CC} 2 V.

Table 5. 100ELT SERIES PECL DC CHARACTERISTICS V_{CC} = 5.0 V; GND = 0.0 V (Note 5)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{CC}	Power Supply Current			16			16			16	mA
V _{OH}	Output HIGH Voltage (Note 6)	3915	3995	4120	3975	4045	4120	3975	4050	4120	mV
V _{OL}	Output LOW Voltage (Note 6)	3170	3305	3445	3190	3295	3380	3190	3295	3380	mV
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current	0.5			0.5			0.5			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 5. Output parameters vary 1:1 with V_{CC} . V_{CC} can vary ± 0.25 V.
- 6. Outputs are terminated through a 50 Ω resistor to V_{CC} 2 V.

Table 6. TTL INPUT DC CHARACTERISTICS $V_{CC} = 4.7 \text{ V}$ to 5.27 V; $T_A = -40 ^{\circ}\text{C}$ to $85 ^{\circ}\text{C}$

Symbol	Characteristic	Condition	Min	Тур	Max	Unit
I _{IH}	Input HIGH Current	V _{IN} = 2.7 V			20	μΑ
I _{IHH}	Input HIGH Current	V _{IN} = 7.0 V			100	μΑ
I _{IL}	Input LOW Current	V _{IN} = 0.5 V			-0.6	mA
V _{IK}	Input Clamp Diode Voltage	I _{IN} = -18 mA			-1.2	V
V _{IH}	Input HIGH Voltage		2.0			V
V _{IL}	Input LOW Voltage				0.8	V

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 7. AC CHARACTERISTICS $V_{CC} = 4.75 \text{ V}$ to 5.25 V; GND = 0.0 V

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency	100			100			100			MHz
t _{PLH}	Propagation Delay 1.5 V to 50%	0.6	0.82	1.2	0.6	0.82	1.25	0.6	0.83	1.35	ns
t _{PHL}	Propagation Delay 1.5 V to 50%	0.4		1.0	0.5	0.8	1.1	0.7		1.30	ns
t _{JITTER}	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
t _r /t _f	Output Rise/Fall Time (20-80%)	0.15		1.5	0.15		1.5	0.15		1.5	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

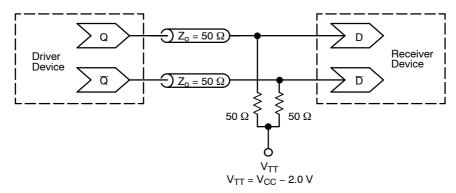


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC10ELT20D	SO-8	98 Units / Rail
MC10ELT20DG	SO-8 (Pb-Free)	98 Units / Rail
MC10ELT20DR2	SO-8	2500 / Tape & Reel
MC10ELT20DR2G	SO-8 (Pb-Free)	2500 / Tape & Reel
MC10ELT20DT	TSSOP-8	100 Units / Rail
MC10ELT20DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC10ELT20DTR2	TSSOP-8	2500 / Tape & Reel
MC10ELT20DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC10ELT20MNR4	DFN8	1000 / Tape & Reel
MC10ELT20MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel
MC100ELT20D	SO-8	98 Units / Rail
MC100ELT20DG	SO-8 (Pb-Free)	98 Units / Rail
MC100ELT20DR2	SO-8	2500 / Tape & Reel
MC100ELT20DR2G	SO-8 (Pb-Free)	2500 / Tape & Reel
MC100ELT20DT	TSSOP-8	100 Units / Rail
MC100ELT20DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100ELT20DTR2	TSSOP-8	2500 / Tape & Reel
MC100ELT20DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100ELT20MNR4	DFN8	1000 / Tape & Reel
MC100ELT20MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide
AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

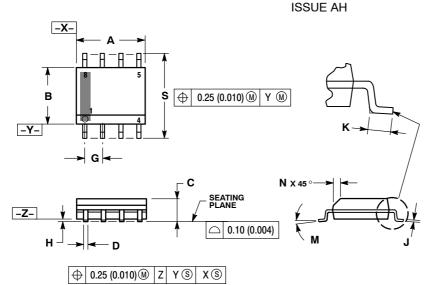
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07

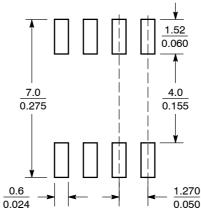


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.

- MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIN	IETERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α	4.80	5.00	0.189	0.197		
В	3.80	4.00	0.150	0.157		
C	1.35	1.75	0.053	0.069		
ם	0.33	0.51	0.013	0.020		
G	1.27	7 BSC	0.050 BSC			
H	0.10	0.25	0.004	0.010		
7	0.19	0.25	0.007	0.010		
K	0.40	1.27	0.016	0.050		
М	0 °	8 °	0 °	8 °		
N	0.25	0.50	0.010	0.020		
S	5.80	6.20	0.228	0.244		

SOLDERING FOOTPRINT*

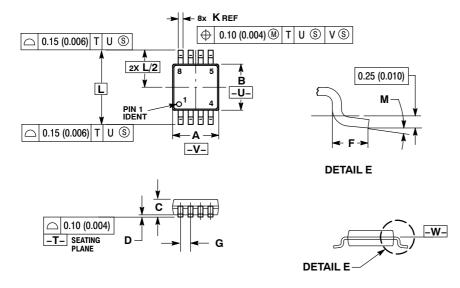


SCALE 6:1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

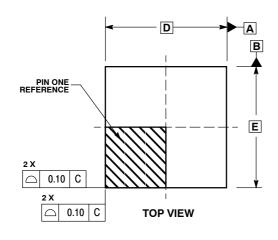
 5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

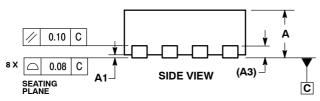
 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W-.

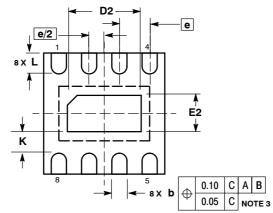
	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	2.90	3.10	0.114	0.122	
В	2.90	3.10	0.114	0.122	
С	0.80	1.10	0.031	0.043	
D	0.05	0.15	0.002	0.006	
F	0.40	0.70	0.016	0.028	
G	0.65	BSC	0.026	BSC	
K	0.25	0.40	0.010	0.016	
L	4.90	BSC	0.193 BSC		
М	0°	6 °	0°	6°	

PACKAGE DIMENSIONS

DFN8 CASE 506AA-01 ISSUE D







NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
- 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS					
DIM	MIN	MAX				
Α	0.80	1.00				
A1	0.00	0.05				
АЗ	0.20	REF				
b	0.20	0.30				
D	2.00	BSC				
D2	1.10	1.30				
E	2.00	BSC				
E2	0.70	0.90				
е	0.50	BSC				
K	0.20					
L	0.25	0.35				

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